

Features

1) Low on - resistance.

4) Halogen Free.

Application

Switching Load switch

RQ3C150BC

Pch -20V -30A Middle Power MOSFET

Datasheet

V _{DSS}	-20V
R _{DS(on)} (Max.)	6.7mΩ
I _D	±30A
P _D	20W

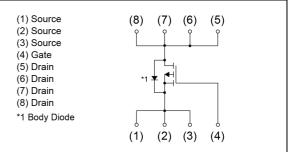
2) High Power small mold Package (HSMT8).

3) Pb-free lead plating ; RoHS compliant.

HSMT8

Inner circuit

Outline



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	12
	Basic ordering unit (pcs)	3000
	Taping code	ТВ
	Marking	C150BC

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Paramete	Symbol	Value	Unit	
Drain - Source voltage	V _{DSS}	-20	V	
Continuous durin cumont	$T_c = 25^{\circ}C$	۱ _D *1	±30	А
Continuous drain current	$T_a = 25^{\circ}C$	I _D	±15	А
Pulsed drain current	I _{D,pulse} *2	±60	А	
Gate - Source voltage	V _{GSS}	±8	V	
Avalanche energy, single pulse	E _{AS} *3	33	mJ	
Avalanche current	I_{AS}^{*3}	-15	А	
Dower dissipation	P _D ^{*1}	20	W	
Power dissipation	P _D ^{*4}	2	W	
Junction temperature	Tj	150	°C	
Range of storage temperature	T _{stg}	-55 to +150	°C	

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•Thermal resistance

Deremeter	Sumbol	Values			L locit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *1	-	-	6.2	°C/W
Thermal resistance, junction - ambient	R_{thJA}^{*4}	-	-	62.5	°C/W

• Electrical characteristics (T_a = 25°C)

Devenueter	Currente e l	Canditiana	Values			1.1:4	
Parameter	Symbol Conditions		Min.	Vin. Typ. Max		- Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -1mA	-20	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	-10.3	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	I_{DSS} V_{DS} = -20V, V_{GS} = 0V		-	-1	μA	
Gate - Source leakage current	ate - Source leakage current I_{GSS} $V_{GS} = \pm 8V, V_{DS} = 0V$		-	-	±100	nA	
Gate threshold voltage	Gate threshold voltage $V_{GS(th)}$ $V_{DS} = V$		-0.5	-	-1.2	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	1.7	-	mV/°C	
		V _{GS} = -4.5V, I _D = -15A	-	4.8	6.7		
Static drain - source on - state resistance	R _{DS(on)} *5	V _{GS} = -2.5V, I _D = -15A	-	6.1	8.5	mΩ	
		V _{GS} = -1.8V, I _D = -3.8A	-	8.8	14		
Gate input resistance R _G f=1MHz, open drain		f=1MHz, open drain	-	3.6	-	Ω	
Forward Transfer Admittance	Y _{fs} * ⁵	V _{DS} = -5V, I _D = -15A	25	-	-	S	

*1Tc=25°C, Limited only by maximum temperature allowed.

*2 Pw \leq 10µs, Duty cycle \leq 1%

*3 L \simeq 0.2mH, V_{DD} = -10V, R_G = 25 Ω , STARTING T_j = 25°C Fig.3-1,3-2

*4 Mounted on a Cu boad (40×40×0.8mm)

*5 Pulsed



•Electrical characteristics (T_a = 25°C)

Deremeter	Sumphal	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	4800	-	
Output capacitance	C _{oss}	V _{DS} = -10V	-	890	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	790	-	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq -10V, V_{GS} = -4.5V$	-	26	-	
Rise time	t _r *5	I _D = -7.5A	-	80	-	20
Turn - off delay time	t _{d(off)} *5	R _L ≃ 1.3Ω	-	300	-	ns
Fall time	t _f *5	R _G = 10Ω	-	280	-	

•Gate charge characteristics (T_a = 25°C)

Deremeter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Symbol Conditions		Тур.	Max.	Unit
Total gate charge	Q_g^{*5}	V _{DD} ≃ -10V,	-	60.0	-	
Gate - Source charge	Q _{gs} *5	I _D = -15A,	-	8.0	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = -4.5V	-	20.4	-	

•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

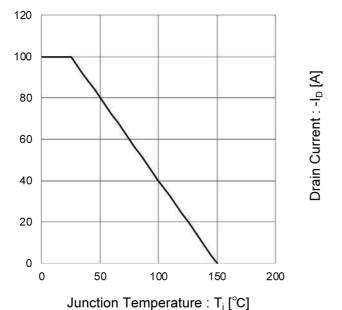
Parameter	Symbol	Conditions	Values			Unit
	neter Symbol Conditions		Min.	Тур.	Max.	Unit
Body diode continuous forward current	I _S	T - 25°0	-	-	-1.67	A
Body diode pulse current	I _{SP} *2	T _a = 25℃	-	-	-60	A
Forward voltage	V_{SD}^{*5}	V _{GS} = 0V, I _S = -1.67A	-	-	-1.2	V



Power Dissipation : P_D/P_D max. [%]







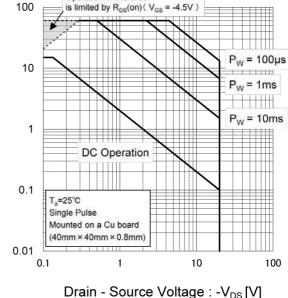
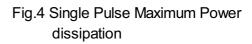
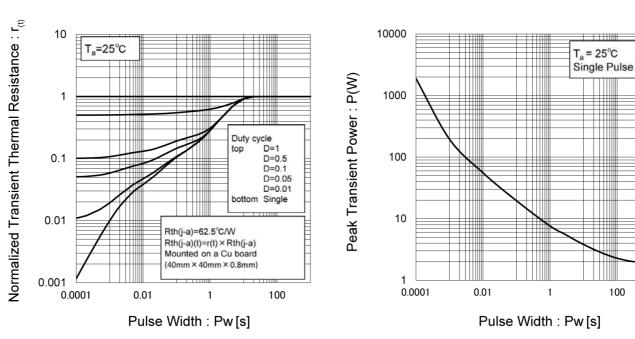


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width







Electrical characteristic curves

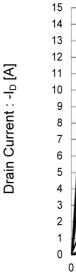


Fig.5 Typical Output Characteristics(I)

T_a=25°C

Pulsed

V_{GS}= -1.2V

V_{GS}= -1.0V

1

≃V_{GS}= -1.5V

V_{GS}= -4.5V

V_{GS}= -2.5V

-V_{GS}= -1.8V

Drain Current : -I_D [A]

3

2

1

0

0

1 2 3 4 5 6 7 8 9 10

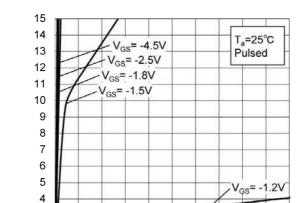


Fig.6 Typical Output Characteristics(II)



V_{GS}= -0.8V

 $V_{GS} = -1.0V$

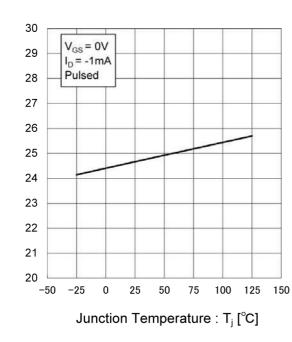
Fig.7 Breakdown Voltage vs. Junction Temperature

V_{GS}= -0.8V

0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9

Drain - Source Voltage : -V_{DS} [V]

Drain-Source Breakdown Voltage : -V_{(BR)DSS} [V]





• Electrical characteristic curves

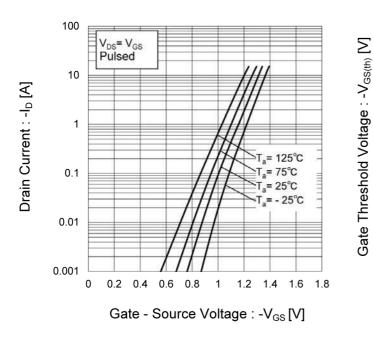


Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature

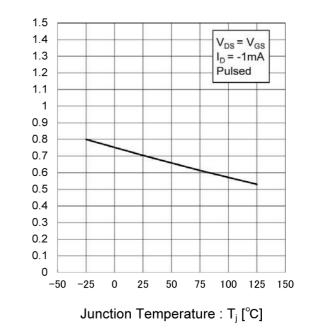
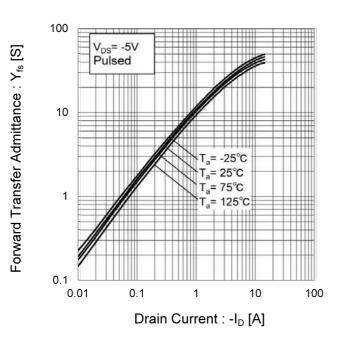


Fig.10 Forward Transfer Admittance vs. Drain Current

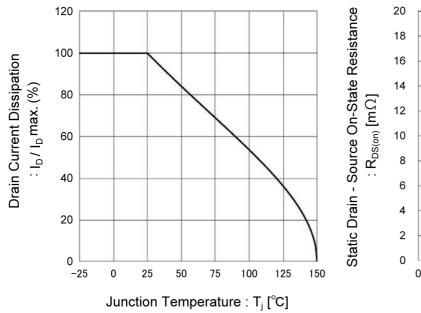


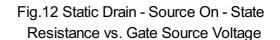
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• Electrical characteristic curves

Fig.11 Drain Current Derating Curve





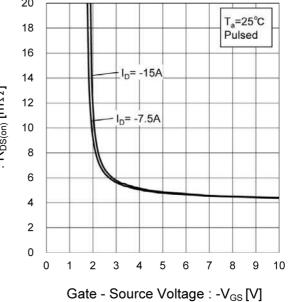
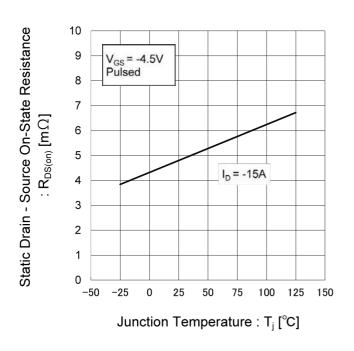


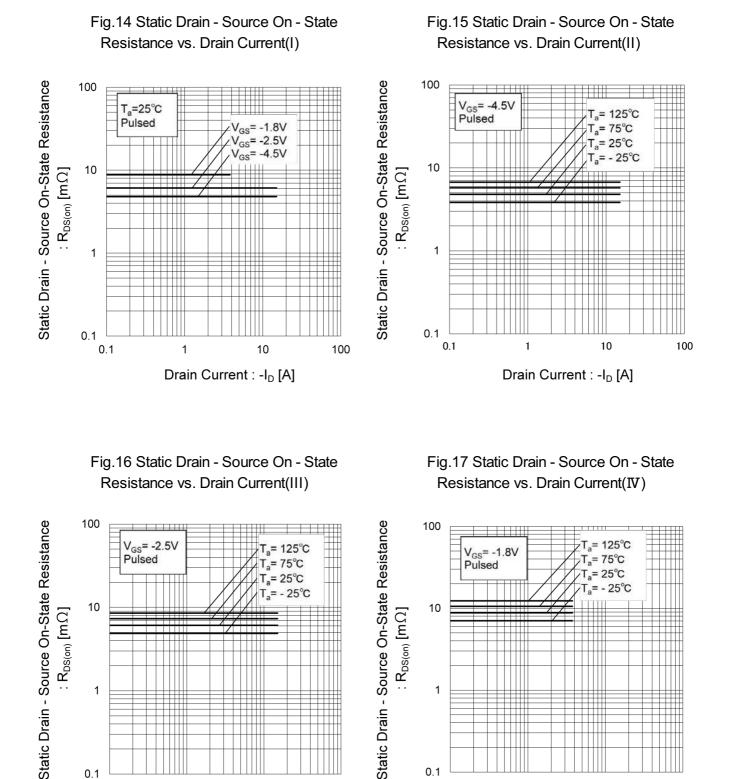
Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



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Electrical characteristic curves





1

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100

10

Drain Current : -I_D [A]

0.1

0.1



1

100

10

Drain Current : -I_D [A]

0.1

0.1

Datasheet

• Electrical characteristic curves

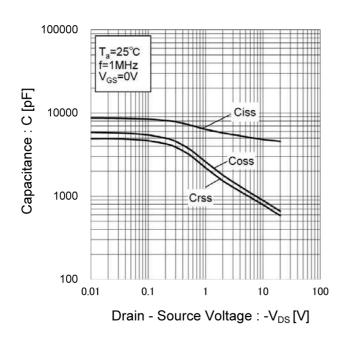


Fig.18 Typical Capacitance vs. Drain -Source Voltage

Fig.19 Switching Characteristics

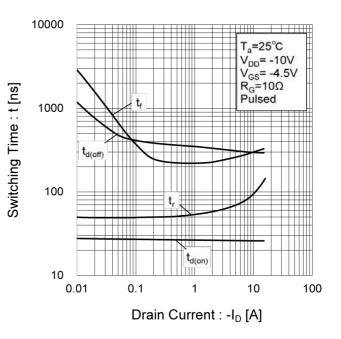


Fig.20 Dynamic Input Characteristics

Gate - Source Voltage : -V_{GS} [V]

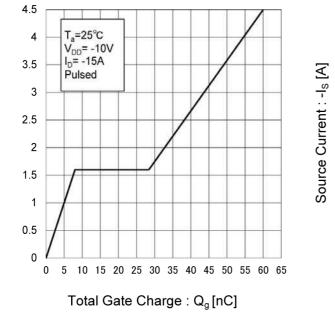
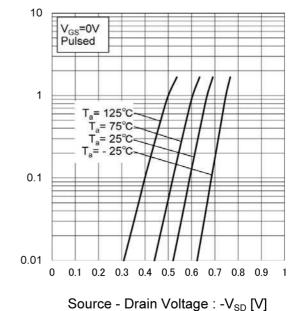
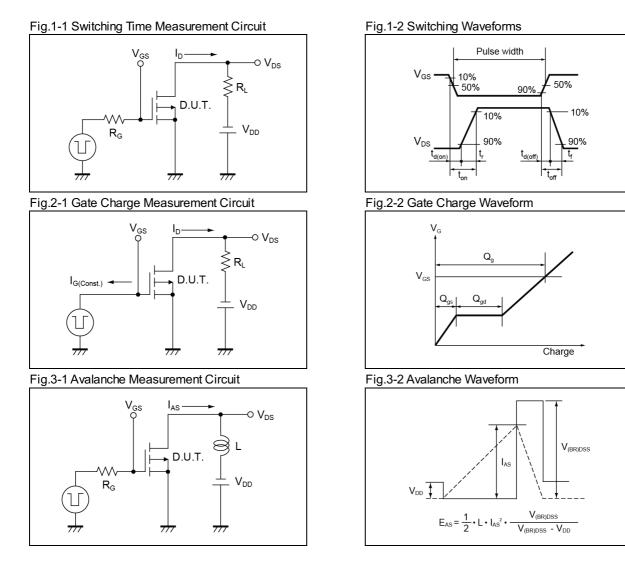


Fig.21 Source Current vs. Source Drain Voltage





Measurement circuits



Notice

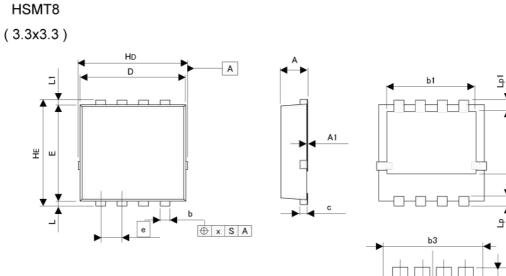
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

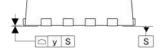
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-p2

Dimensions





٩ 2 <u></u> 4 Ξ е b2

Pattern of terminal position areas [Not a pattern of soldering pads]

DIM -	MILIMETERS		INC	HES
	MIN	MAX	MIN	MAX
A	0.70	0.90	0.028	0.035
A1	0.00	0.05	0.000	0.002
b	0.27	0.37	0.011	0.015
b1	2.50	2.70	0.098	0.106
С	0.10	0.30	0.004	0.012
D	3.10	3.30	0.122	0.130
E	2.90	3.10	0.114	0.122
e	0.	65	0.0	26
HD	3.20	3.40	0.126	0.134
HE	3.20	3.40	0.126	0.134
L	0.07	0.25	0.003	0.010
L1	0.07	0.25	0.003	0.010
Lp	0.20	0.40	0.008	0.016
Lp1	0.25	0.45	0.010	0.018
Lp2	2.20	2.40	0.087	0.094
x	-	0.10		0.004
у		0.10	-	0.004
	MILIME	TERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	121	0.47	-	0.019
b3	-	2.70	-	0.106
11	190	0.50	i = 1	0.020
12	12	0.55	. u	0.022
13	 .	2.40		0.094
14	-	3.40	(<u> </u>	0.134

Dimension in mm/inches



Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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CLASSⅣ	CLASSIII	CLASSⅢ	CLASSII

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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [C] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

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